

AK6-Y Series



Agency Recognitions

AGENCY	AGENCY FILE NUMBER
	E128662

Maximum Ratings and Thermal Characteristics (T_A=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Operating Storage Temperature Range	T _{STG}	-55 to 150	°C
Operating Junction Temperature Range	T _J	-55 to 125	°C
Current Rating ¹	I _{PP}	6	kA

Note:
1. Rated I_{pp} measured with 8/20µs pulse.

Functional Diagram



Description

The AK6-Y series of high power TVS diode is specially designed for meeting severe surge test environment of both AC and DC line protection applications. It features a very fast response and ultra low clamping characteristics as compared to MOVs (Metal Oxide Varistors). It accomplishes this by virtue of the Littelfuse Foldback™ technology, which provides a clamping voltage lower than the avalanche voltage (but above the rated working voltage); therefore, any voltage rise due to increased current conduction is maintained at a minimum magnitude, providing the best possible protection level. These AK components can be connected in series and / or parallel to create a very high surge current protection solution.

Features

- Recognized to UL 497B as an Isolated Loop Circuit Protector
- Both reflow and wave soldering capable
- Very low clamping voltage
- Ultra compact: less than one-tenth the size of traditional discrete solutions
- Sharp breakdown voltage
- Low slope resistance
- Bi-directional
- Foldback technology for superior clamping factor
- Symmetric in leads width for easier soldering during assembly.
- IEC-61000-4-2 ESD 15kV(Air), 8kV (Contact)
- ESD protection of data lines in accordance with IEC 61000-4-2
- EFT protection of data lines in accordance with IEC 61000-4-4
- Halogen-free and RoHS compliant
- Glass passivated junction
- Pb-free E4 means 2nd level interconnect is Pb-free and the terminal finish material is silver

Electrical Characteristics (T_A=25°C unless otherwise noted)

Part Numbers	Part Marking	Standoff Voltage (V _{SO}) Volts	Max. Reverse Leakage (I _R) @ V _{SO} µA	Typical I _R @ 85°C (µA)	Reverse Breakdown Voltage (V _{BR}) @ I _T		Test Current I _T (mA)	Max. Clamping Voltage V _{CL} @ I _{PP} Peak Pulse Current (I _{PP}) (Note 1)		Max. Temp Coefficient OF V _{BR} (%/°C)	Max. Capacitance 0 Bias 10kHz (nF)	Agency Approval
					Min Volts	Max Volts		V _{CL} Volts	I _{PP} Amps			
AK6-030C-Y	6-030C	30	10	15	32	37	10	90	6,000	0.1	11.0	X
AK6-058C-Y	6-058C	58	10	15	64	70	10	110	6,000	0.1	8.0	X
AK6-066C-Y	6-066C	66	10	15	72	80	10	120	6,000	0.1	6.0	X
AK6-076C-Y	6-076C	76	10	15	85	95	10	140	6,000	0.1	6.5	X
AK6-170C-Y	6-170C	170	10	15	180	220	10	260	6,000	0.1	2.8	X
AK6-190C-Y	6-190C	190	10	15	200	245	10	290	6,000	0.1	2.5	X
AK6-240C-Y	6-240C	240	10	15	250	285	10	340	6,000	0.1	2.0	X
AK6-380C-Y	6-380C	380	10	15	401	443	10	520	6,000	0.1	1.4	X
AK6-430C-Y	6-430C	430	10	15	440	490	10	625	6,000	0.1	1.0	X

Note: Using 8/20µs wave shape as defined in IEC 61000-4-5.

Figure 1 - Peak Power Derating

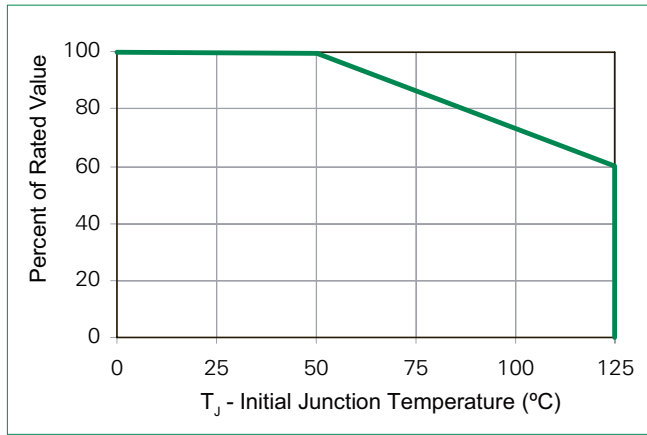


Figure 2 - Pulse Waveform

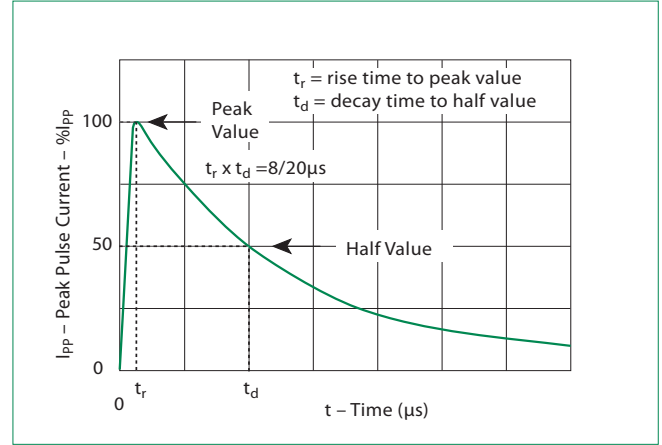


Figure 3 - Typical Peak Pulse Power Rating Curve

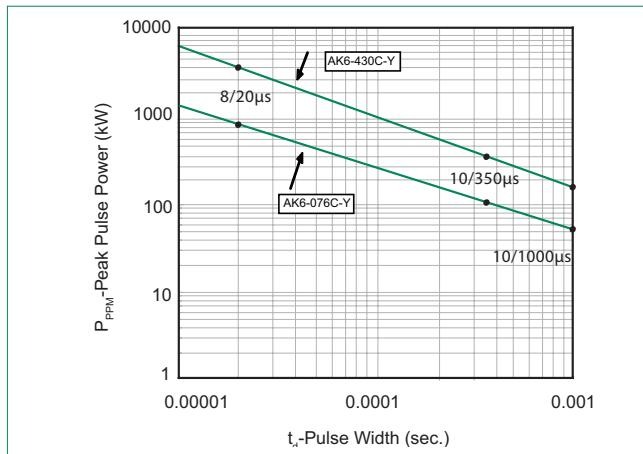


Figure 4 - Typical V_{BR} Vs Junction Temperature

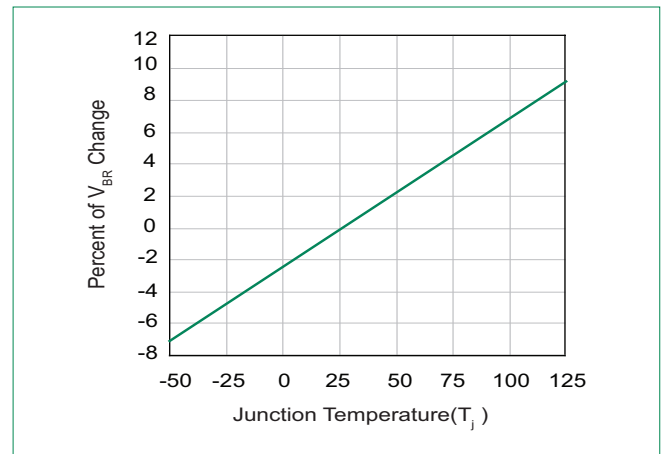
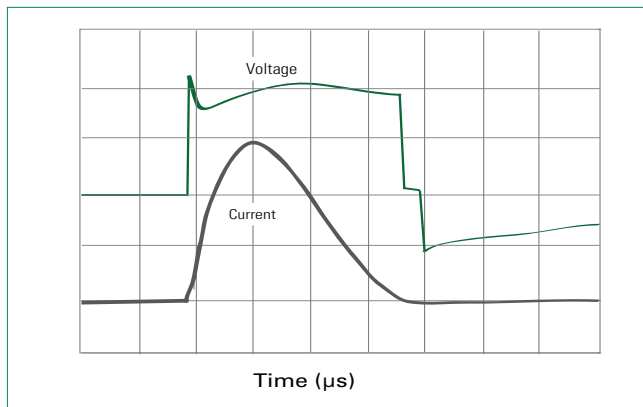


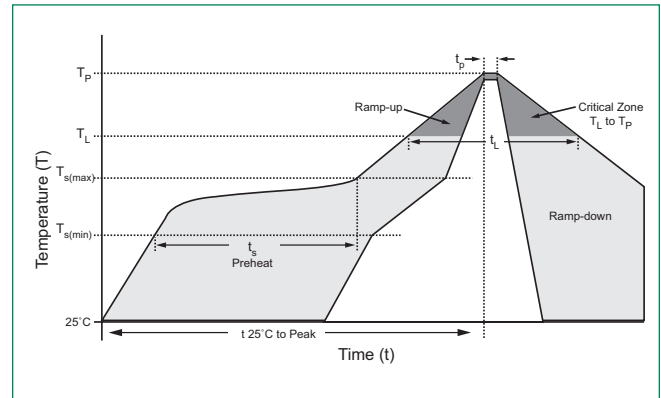
Figure 5 -Surge Response (8/20 Surge current waveform)



Note: The power dissipation causes a change in avalanche voltage during the surge and the avalanche voltage eventually returns to the original value when the transient has passed.

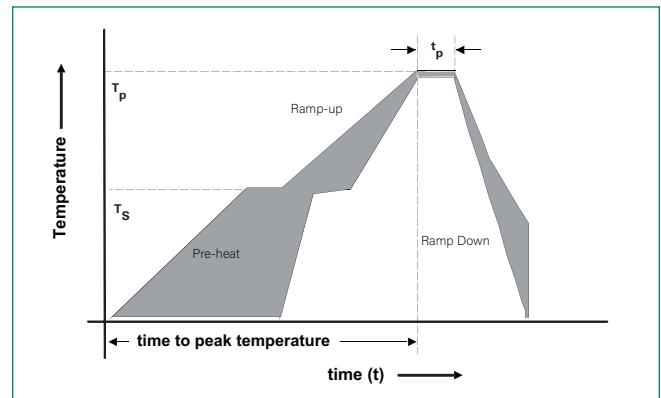
Soldering Parameters

Reflow Condition		Lead-free assembly
Pre Heat	- Temperature Min ($T_{s(min)}$)	150°C
	- Temperature Max ($T_{s(max)}$)	200°C
	- Time (min to max) (t_s)	60 – 120 secs
Average ramp up rate (Liquidus Temp (T_L) to peak)		3°C/second max
$T_{s(max)}$ to T_A - Ramp-up Rate		3°C/second max
Reflow	- Temperature (T_L) (Liquidus)	217°C
	- Time (min to max) (T_S)	60 – 150 seconds
Peak Temperature (T_p)		260 ^{+0/-5} °C
Time within 5°C of actual peak Temperature (t_p)		30 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_p)		8 minutes Max.
Do not exceed		260°C



Flow Soldering (Solder Dipping)

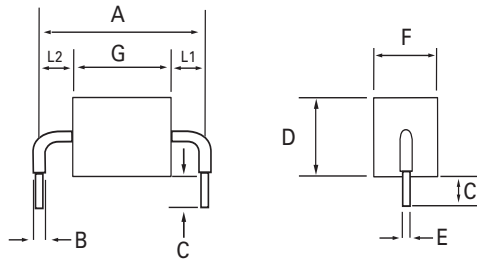
Reflow Condition		Lead-free assembly
Pre Heat	- Temperature Min ($T_{s(min)}$)	140°C
	- Temperature Max ($T_{s(max)}$)	160°C
	- Time to Pre-Heat Temp	60 – 150 secs
Average ramp up rate to Pre-Heat Temp		5°C/second max
Peak Temperature (T_p)		260 ^{+0/-5} °C
Average ramp up rate (pre-heat to T_p)		5°C/second max
Time within actual peak Temperature Max		6 seconds
Ramp-down Rate		5°C/second max



Physical Specifications

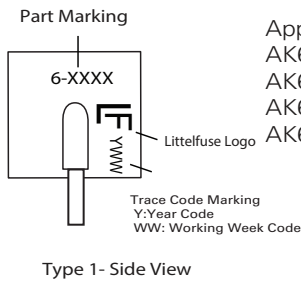
Weight	Contact manufacturer
Case	UL Recognized compound meeting flammability rating V-0
Terminal	Silver plated leads, solderable per MIL-STD-750 Method 2026

Dimensions

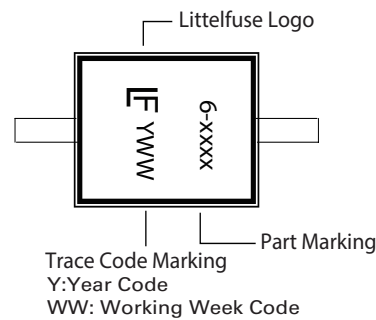


Dimensions	Inches	Millimeters
A	0.950 +/- 0.040	24.15 +/- 1.00
B	0.095 +/- 0.024	2.4 +/- 0.60
C	0.236 +/- 0.040	6.00 +/- 1.00
D	0.570 max.	14.48 max.
E	0.050 +/- 0.002	1.270 +/- 0.05
F	0.500 max.	12.70 max.
G - 030C-Y	0.161 +/- 0.040	4.10 +/- 1.00
G - 058C-Y/066C-Y 076C-Y	0.189 +/- 0.040	4.8 +/- 1.00
G - 170C-Y/190C-Y	0.320 +/- 0.040	8.13 +/- 1.00
G - 240C-Y	0.370 +/- 0.040	9.4 +/- 1.00
G - 380C-Y/430C-Y	0.543 +/- 0.040	13.8 +/- 1.00
L1/L2	L1= L2 tolerance +/- 0.04 inch (1.0 mm)	

Part Marking System

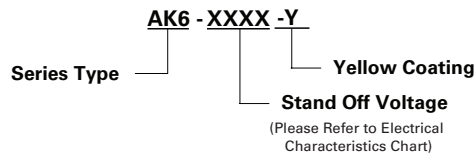


Apply to P/N listed below:
AK6-030C-Y
AK6-058C-Y
AK6-066C-Y
AK6-076C-Y



Apply to P/N listed below:
AK6-170C-Y
AK6-190C-Y
AK6-240C-Y
AK6-380C-Y
AK6-430C-Y

Part Numbering System



Packing Options

Part Number	Component Package	Quantity	Packaging Option
AK6-XXXX-Y	AK Package	56pcs/Box	Bulk
AK6-XXXX-Y12	AK Package	12pcs/Box	Bulk

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